



Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D $T_A = 25^\circ C$
-30V	25m Ω @ $V_{GS} = -10V$	-16.1A
	41m Ω @ $V_{GS} = -4.5V$	-12.5A

Description and Applications

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

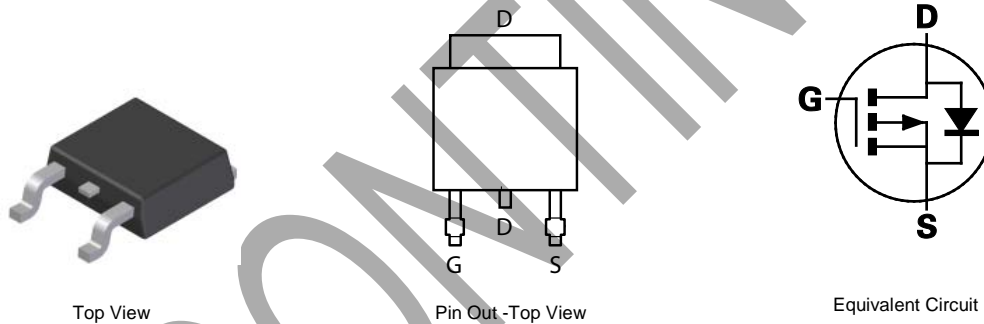
- Backlighting
- DC-DC Converters
- Power management functions

Features and Benefits

- Low on-resistance
- Fast switching speed
- "Green" component and RoHS compliant (Note 1)

Mechanical Data

- Case: TO252-3L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Below
- Ordering Information: See Below
- Weight: 0.33 grams (approximate)



Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMP3025LK3-13	P3025L	13	16	2,500

Note: 1. Diodes, Inc. defines "Green" products as those which are Eu RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

Marking Information



D = Manufacturer's Marking
P3025L = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 09 = 2009)
WW = Week (01-52)

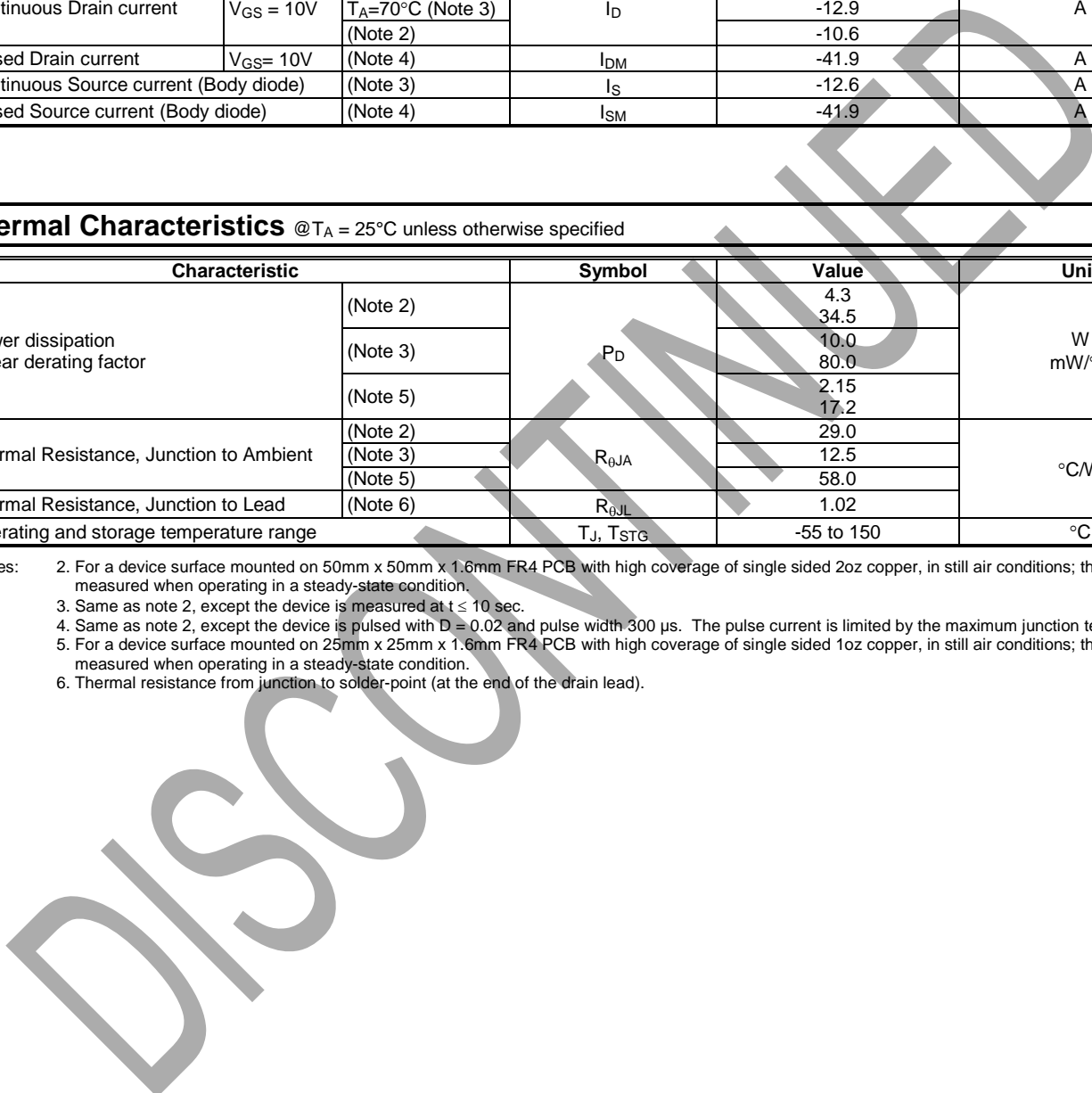
Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic			Symbol	Value	Unit	
Drain-Source voltage			V_{DSS}	-30	V	
Gate-Source voltage			V_{GS}	± 20	V	
Continuous Drain current	$V_{GS} = 10\text{V}$	(Note 3)	I_D	-16.1	A	
		$T_A = 70^\circ\text{C}$ (Note 3)		-12.9		
		(Note 2)		-10.6		
Pulsed Drain current	$V_{GS} = 10\text{V}$	(Note 4)	I_{DM}	-41.9	A	
Continuous Source current (Body diode)			(Note 3)	I_S	-12.6	A
Pulsed Source current (Body diode)			(Note 4)	I_{SM}	-41.9	A

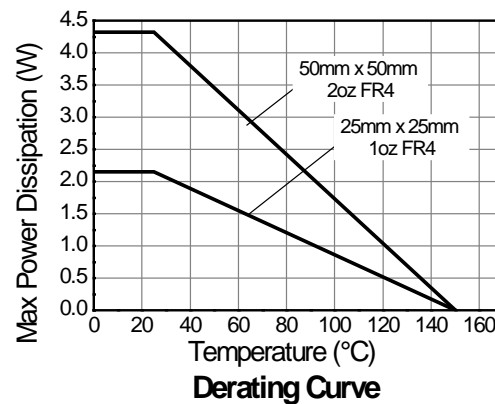
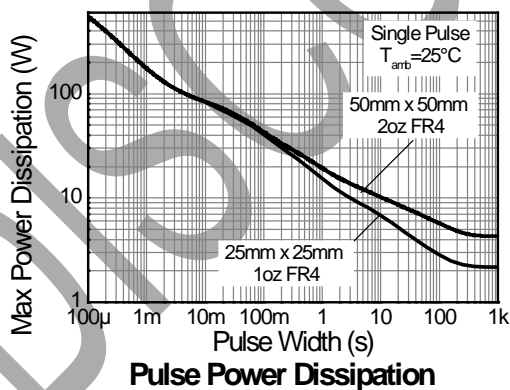
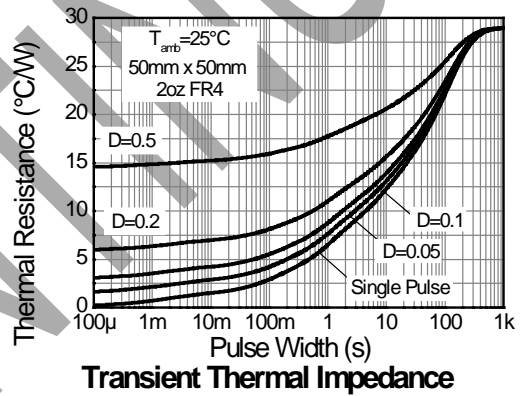
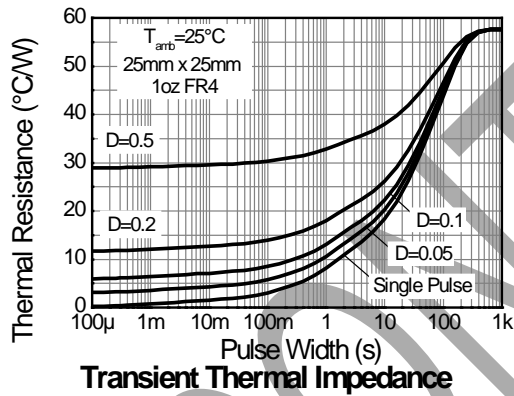
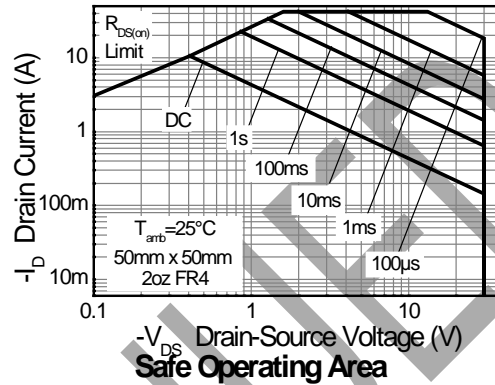
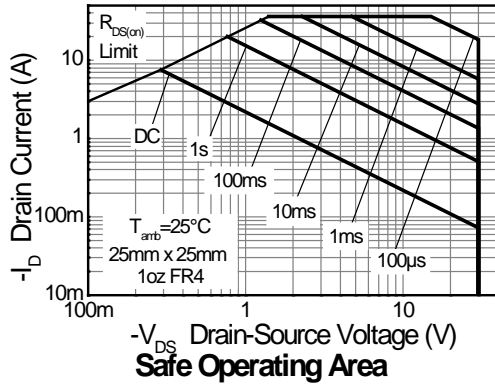
Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic		Symbol	Value	Unit
Power dissipation Linear derating factor	(Note 2)	P_D	4.3	W mW/ $^\circ\text{C}$
			34.5	
	(Note 3)		10.0	
			80.0	
	(Note 5)		2.15	
Thermal Resistance, Junction to Ambient	(Note 2)	$R_{\theta JA}$	29.0	$^\circ\text{C/W}$
	(Note 3)		12.5	
	(Note 5)		58.0	
Thermal Resistance, Junction to Lead	(Note 6)	$R_{\theta JL}$	1.02	$^\circ\text{C}$
Operating and storage temperature range		T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

- Notes:
2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 3. Same as note 2, except the device is measured at $t \leq 10$ sec.
 4. Same as note 2, except the device is pulsed with $D = 0.02$ and pulse width 300 μs . The pulse current is limited by the maximum junction temperature.
 5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 6. Thermal resistance from junction to solder-point (at the end of the drain lead).



Thermal Characteristics



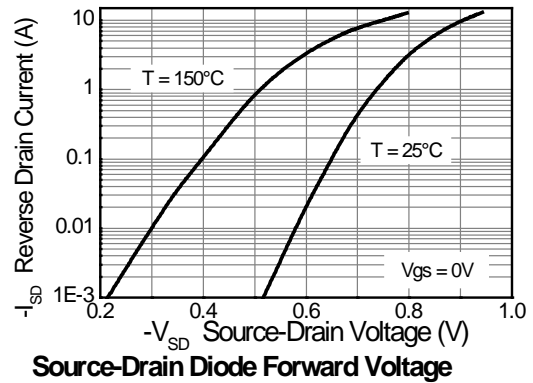
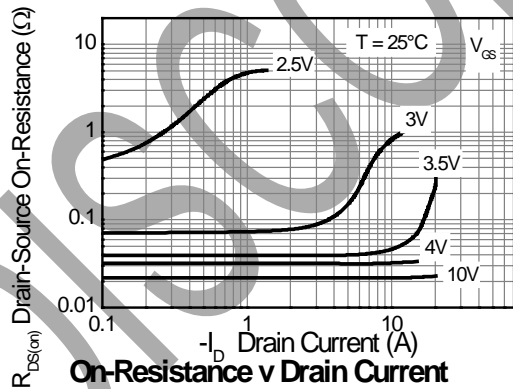
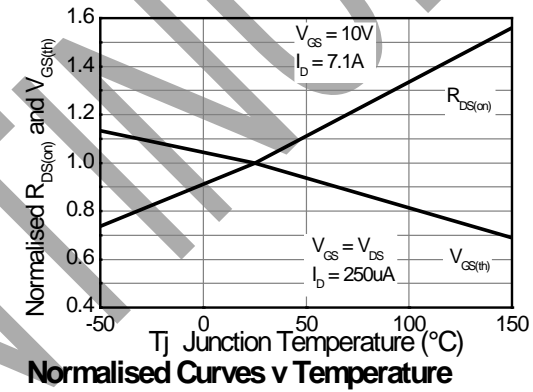
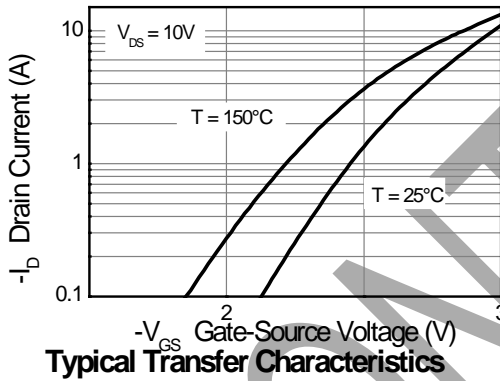
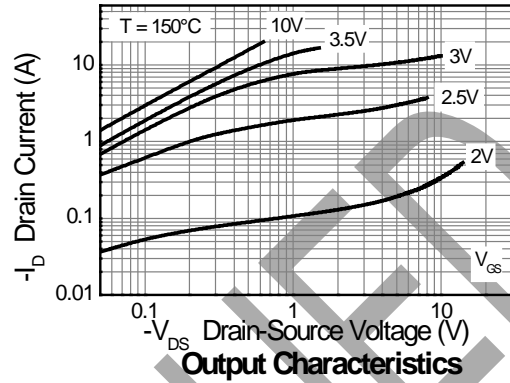
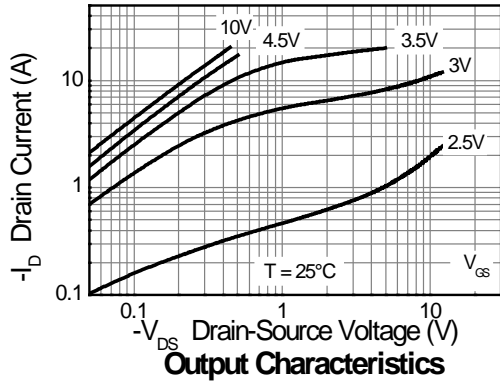
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	-30	—	—	V	I _D = -250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-0.5	μA	V _{DS} = -30V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	-1.0	—	-3.0	V	I _D = -250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance (Note 7)	R _{DS(on)}	—	—	0.025	•	V _{GS} = -10V, I _D = -7.1A
				0.041		V _{GS} = -4.5V, I _D = -5.5A
Forward Transconductance (Notes 7 & 8)	g _{fs}	—	18.6	—	S	V _{DS} = -15V, I _D = -7.1A
Diode Forward Voltage (Note 7)	V _{SD}	—	-0.80	-1.2	V	I _S = -1.7A, V _{GS} = 0V
Reverse recovery time (Note 8)	t _{rr}	—	16.2	—	ns	I _S = -2.2A, di/dt = 100A/μs
Reverse recovery charge (Note 8)	Q _{rr}	—	10	—	nC	
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	1678	—	pF	V _{DS} = -15V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oss}	—	303	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	178	—	pF	
Total Gate Charge	Q _g	—	16.5	—	nC	V _{GS} = -4.5V
Total Gate Charge	Q _g	—	31.6	—	nC	V _{GS} = -10V
Gate-Source Charge	Q _{gs}	—	4.3	—	nC	
Gate-Drain Charge	Q _{gd}	—	6.2	—	nC	
Turn-On Delay Time (Note 9)	t _{D(on)}	—	3.5	—	ns	V _{DD} = -15V, V _{GS} = -10V I _D = -1A, R _G = 6.0Ω
Turn-On Rise Time (Note 9)	t _r	—	4.9	—	ns	
Turn-Off Delay Time (Note 9)	t _{D(off)}	—	44	—	ns	
Turn-Off Fall Time (Note 9)	t _f	—	23	—	ns	

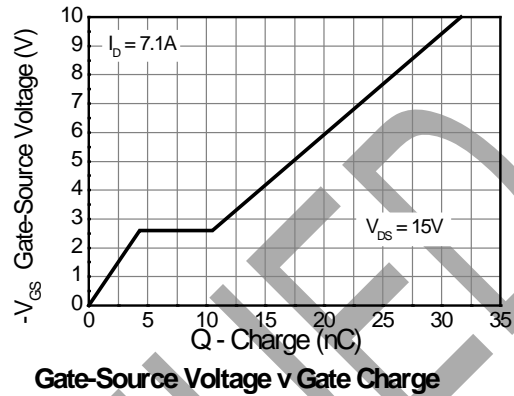
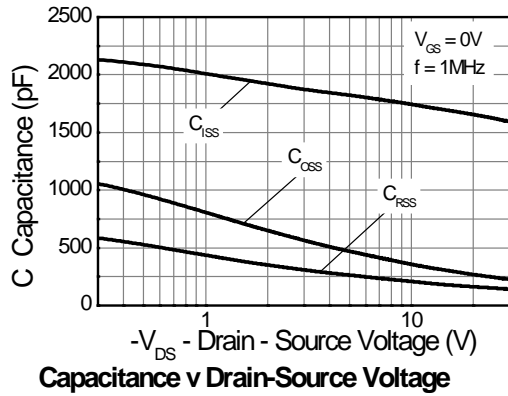
- Notes:
7. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%
 8. For design aid only, not subject to production testing.
 9. Switching characteristics are independent of operating junction temperatures.

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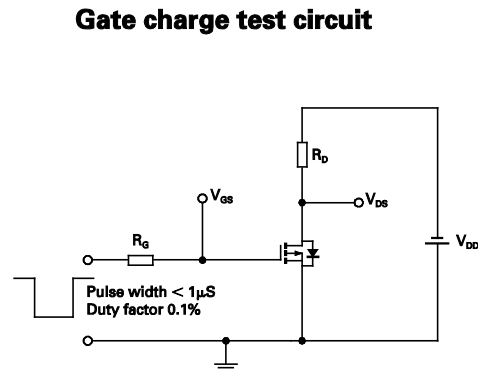
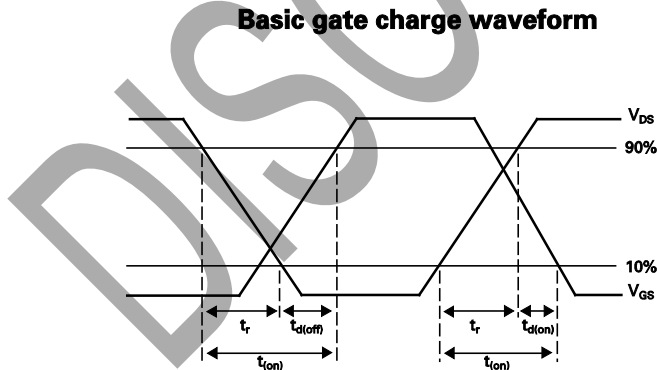
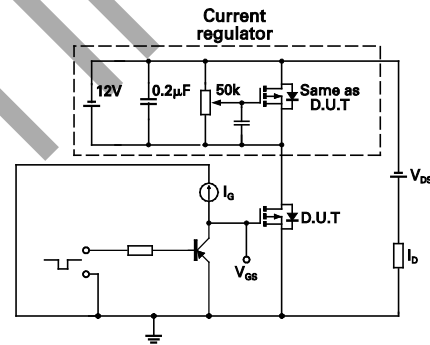
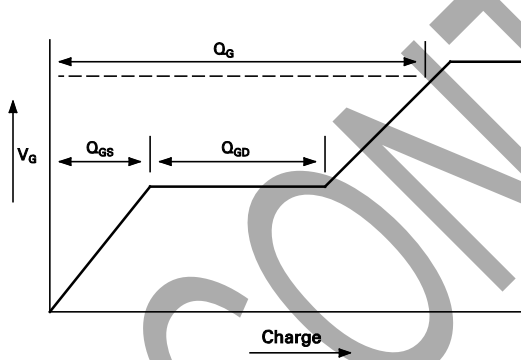
Typical Characteristics



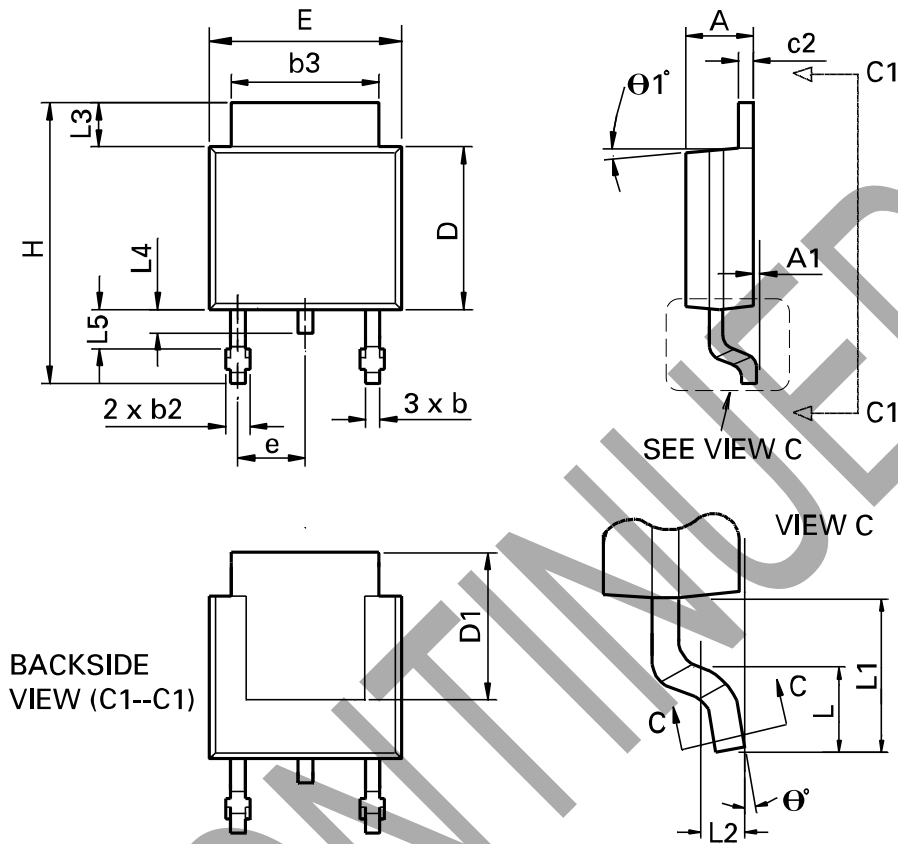
Typical Characteristics - continued



Test Circuits

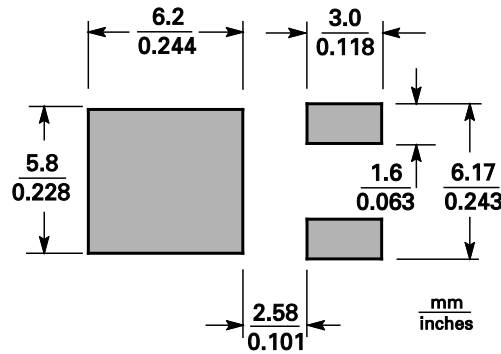


Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
A	0.086	0.094	2.18	2.39	e	0.090 BSC		2.29 BSC	
A1	-	0.005	-	0.127	H	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
c	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	$\bullet 1^\circ$	0°	10°	0°	10°
E	0.250	0.265	6.35	6.73	\bullet°	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-

Suggested Pad Layout



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